



**THE DATASHEET OF  
DMT6009LPS-13**



## Product Summary

BV <sub>DSS</sub>	R <sub>DS(ON)</sub> Max	I <sub>D</sub> T <sub>C</sub> = +25°C
60V	10mΩ @ V <sub>GS</sub> = 10V	87A
	12mΩ @ V <sub>GS</sub> = 4.5V	79A

## Description and Applications

This MOSFET is designed to minimize the on-state resistance (R<sub>DS(ON)</sub>) yet maintain superior switching performance, making it ideal for high-efficiency power-management applications.

- High frequency switching
- Sync. rectification
- DC-DC converters

## Features

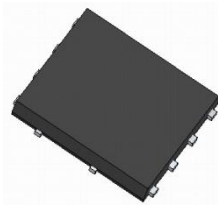
- 100% Unclamped Inductive Switching – Ensures More Reliable and Robust End Application
- Low R<sub>DS(ON)</sub> – Minimizes Power Losses
- Low Q<sub>g</sub> – Minimizes Switching Losses
- **Lead-Free Finish; RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. “Green” Device (Note 3)**
- **For automotive applications requiring specific change control (i.e.: parts qualified to AEC-Q100/101/104/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please refer to the related automotive grade (Q-suffix) part. A listing can be found at <https://www.diodes.com/products/automotive/automotive-products/>.**
- **This part is qualified to JEDEC standards (as references in AEC-Q) for High Reliability.**  
<https://www.diodes.com/quality/product-definitions/>

## Mechanical Data

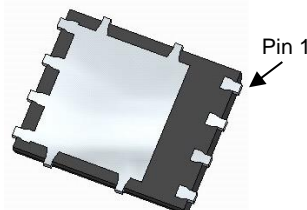
- Package: PowerDI<sup>®</sup>5060-8
- Package Material: Molded Plastic, “Green” Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Finish – Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 (e3)
- Weight: 0.097 grams (Approximate)

Site 1:

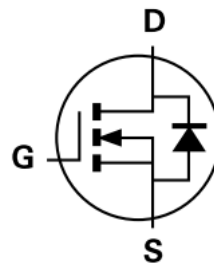
PowerDI5060-8



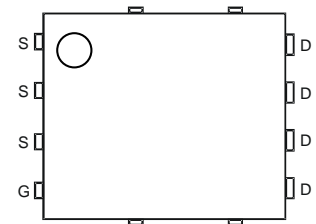
Top View



Bottom View



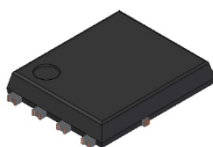
Internal Schematic



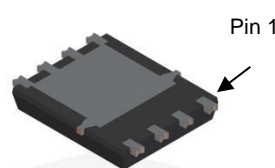
Top View  
Pin Configuration

Site 2:

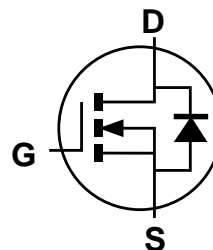
PowerDI5060-8/SWP (Type UX)



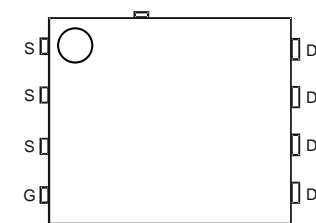
Top View



Bottom View



Internal Schematic



Top View  
Pin Configuration

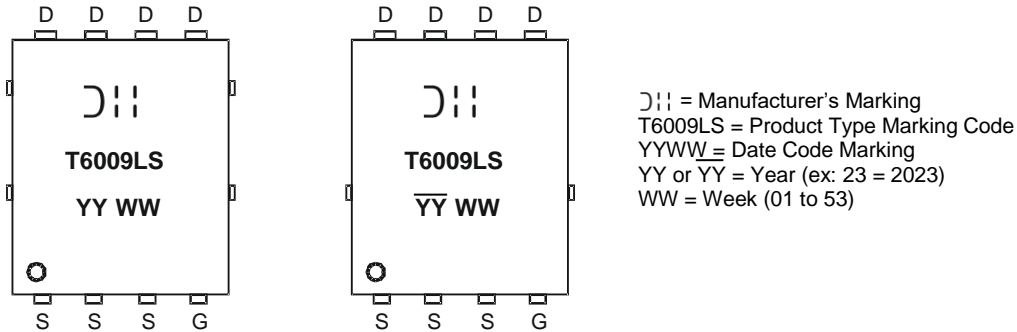
- Notes:
1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied.
  2. See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

### Ordering Information (Note 4)

Part Number	Package	Packing	
		Qty.	Carrier
DMT6009LPS-13	PowerDI5060-8	2,500	Tape & Reel
	PowerDI5060-8/SWP (Type UX)	2,500	Tape & Reel

Note: 4. For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.

### Marking Information



### Maximum Ratings (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Units
Drain-Source Voltage	V <sub>DSS</sub>	60	V
Gate-Source Voltage	V <sub>GSS</sub>	±16	V
Continuous Drain Current (Note 5)	I <sub>D</sub>	T <sub>A</sub> = +25°C	10.6
		T <sub>A</sub> = +70°C	9.1
Continuous Drain Current (Note 6)	I <sub>D</sub>	T <sub>C</sub> = +25°C	87
		T <sub>C</sub> = +70°C	69
Maximum Continuous Body Diode Forward Current (Note 6)	I <sub>S</sub>	100	A
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)	I <sub>DM</sub>	160	A
Avalanche Current, L = 0.1mH	I <sub>AS</sub>	20.3	A
Avalanche Energy, L = 0.1mH	E <sub>AS</sub>	20.6	mJ

### Thermal Characteristics

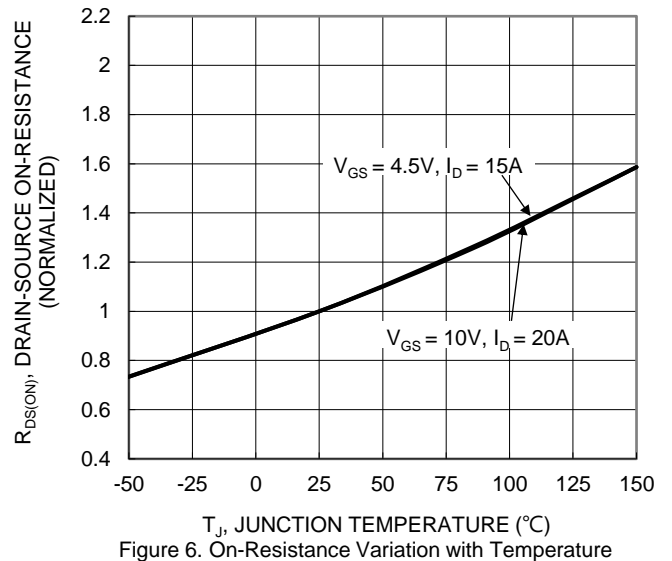
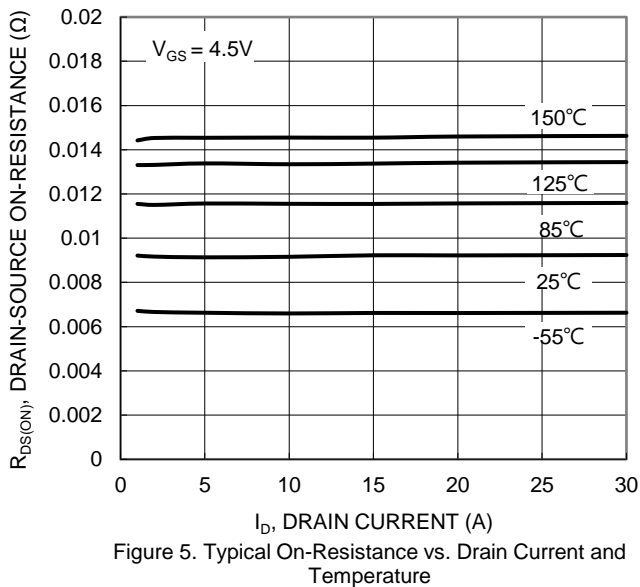
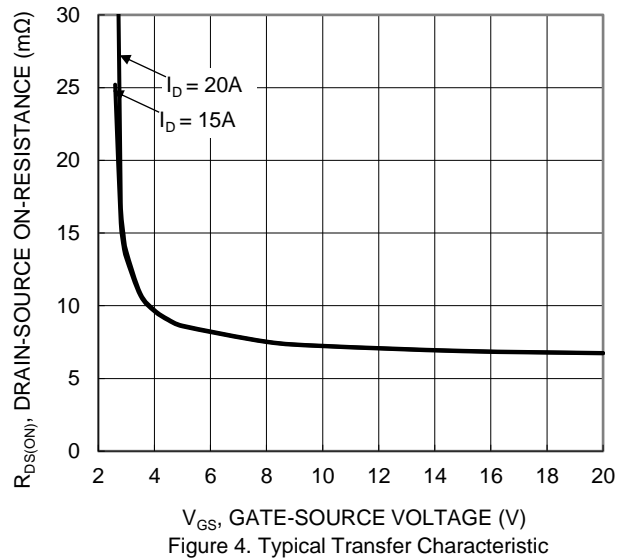
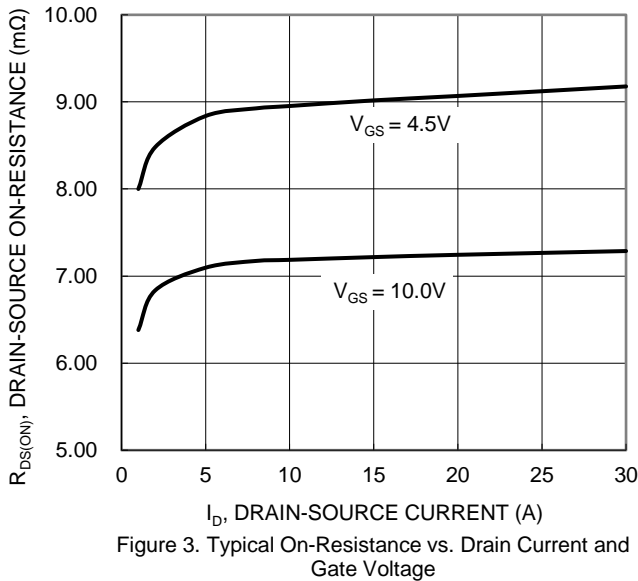
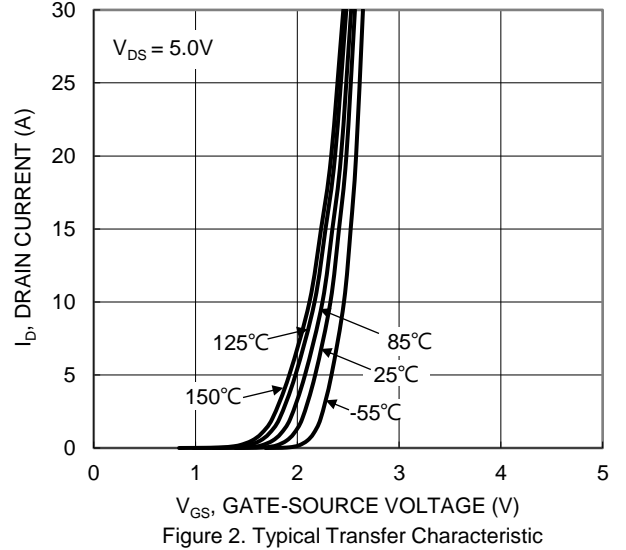
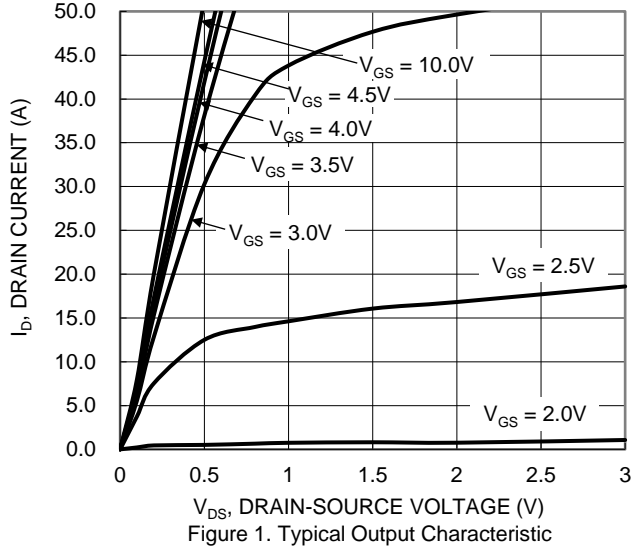
Characteristic	Symbol	Value	Units
Total Power Dissipation (Note 5)	P <sub>D</sub>	2.3	W
Thermal Resistance, Junction to Ambient (Note 5)	R <sub>θJA</sub>	53	°C/W
Total Power Dissipation (Note 6)	P <sub>D</sub>	113	W
Thermal Resistance, Junction to Case (Note 6)	R <sub>θJC</sub>	1.1	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

Notes: 5. Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1inch square copper plate.  
 6. Thermal resistance from junction to soldering point (on the exposed drain pad).

**Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
<b>OFF CHARACTERISTICS (Note 7)</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	60	—	—	V	V <sub>GS</sub> = 0V, I <sub>D</sub> = 1mA
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	—	—	1	μA	V <sub>DS</sub> = 48V, V <sub>GS</sub> = 0V
Gate-Source Leakage	I <sub>GSS</sub>	—	—	±100	nA	V <sub>GS</sub> = ±16V, V <sub>DS</sub> = 0V
<b>ON CHARACTERISTICS (Note 7)</b>						
Gate Threshold Voltage	V <sub>GS(TH)</sub>	0.7	—	2	V	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA
Static Drain-Source On-Resistance	R <sub>DS(ON)</sub>	—	7.2	10	mΩ	V <sub>GS</sub> = 10V, I <sub>D</sub> = 20A
		—	8.9	12		V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 15A
Diode Forward Voltage	V <sub>SD</sub>	—	0.9	—	V	V <sub>GS</sub> = 0V, I <sub>S</sub> = 20A
<b>DYNAMIC CHARACTERISTICS (Note 8)</b>						
Input Capacitance	C <sub>iss</sub>	—	1,925	—	pF	V <sub>DS</sub> = 30V, V <sub>GS</sub> = 0V f = 1MHz
Output Capacitance	C <sub>oss</sub>	—	438	—		
Reverse Transfer Capacitance	C <sub>rss</sub>	—	41	—		
Gate Resistance	R <sub>G</sub>	—	1.7	—	Ω	V <sub>DS</sub> = 0V, V <sub>GS</sub> = 0V, f = 1MHz
Total Gate Charge (V <sub>GS</sub> = 10V)	Q <sub>g</sub>	—	33.5	—	nC	V <sub>DS</sub> = 30V, I <sub>D</sub> = 13.5A
Total Gate Charge (V <sub>GS</sub> = 4.5V)	Q <sub>g</sub>	—	15.6	—		
Gate-Source Charge	Q <sub>gs</sub>	—	4.7	—		
Gate-Drain Charge	Q <sub>gd</sub>	—	5.3	—		
Turn-On Delay Time	t <sub>D(ON)</sub>	—	4.5	—	ns	V <sub>DD</sub> = 30V, V <sub>GS</sub> = 10V R <sub>G</sub> = 6Ω, I <sub>D</sub> = 13.5A
Turn-On Rise Time	t <sub>R</sub>	—	8.6	—		
Turn-Off Delay Time	t <sub>D(OFF)</sub>	—	35.9	—		
Turn-Off Fall Time	t <sub>F</sub>	—	15.7	—		
Body Diode Reverse Recovery Time	t <sub>RR</sub>	—	18.2	—	ns	I <sub>F</sub> = 13.5A, di/dt = 400A/μs
Body Diode Reverse Recovery Charge	Q <sub>RR</sub>	—	33.1	—	nC	

Notes: 7. Short duration pulse test used to minimize self-heating effect.  
8. Guaranteed by design. Not subject to product testing.



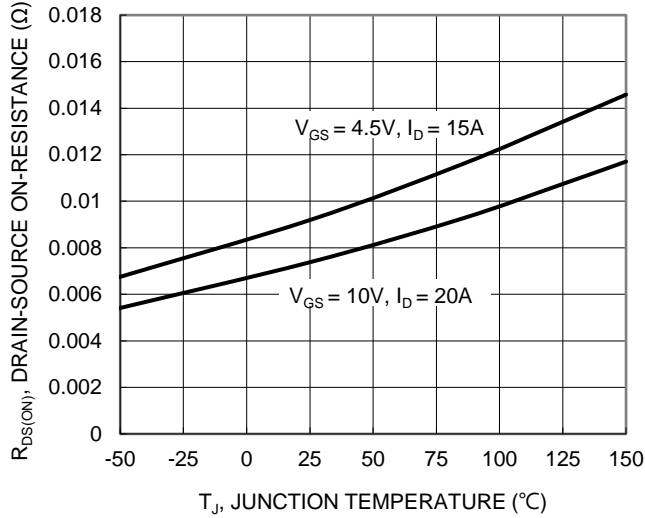


Figure 7. On-Resistance Variation with Temperature

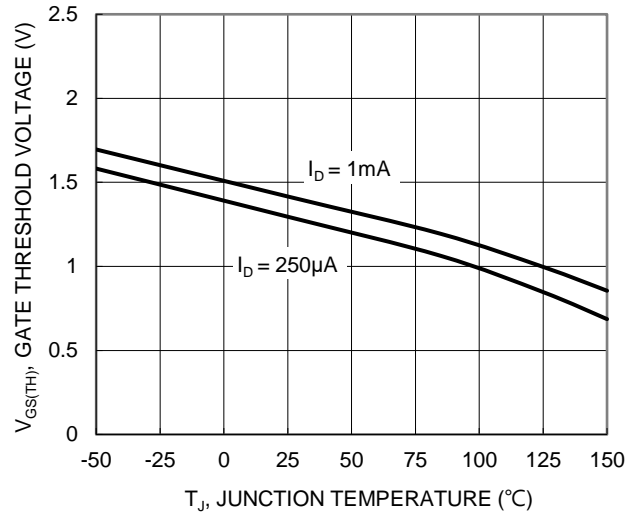


Figure 8. Gate Threshold Variation vs. Junction Temperature

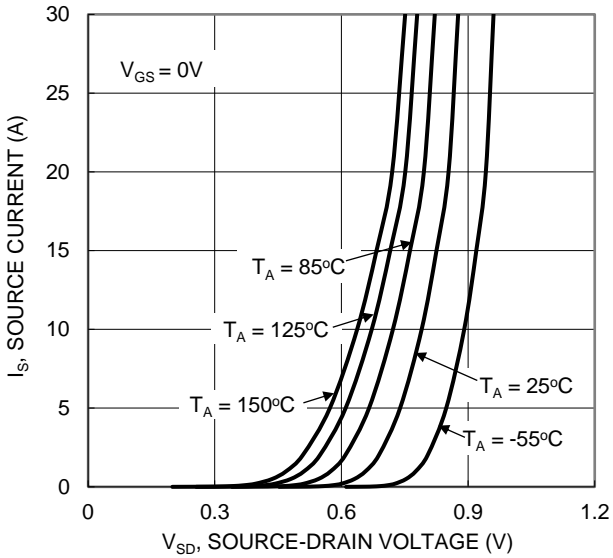


Figure 9. Diode Forward Voltage vs. Current

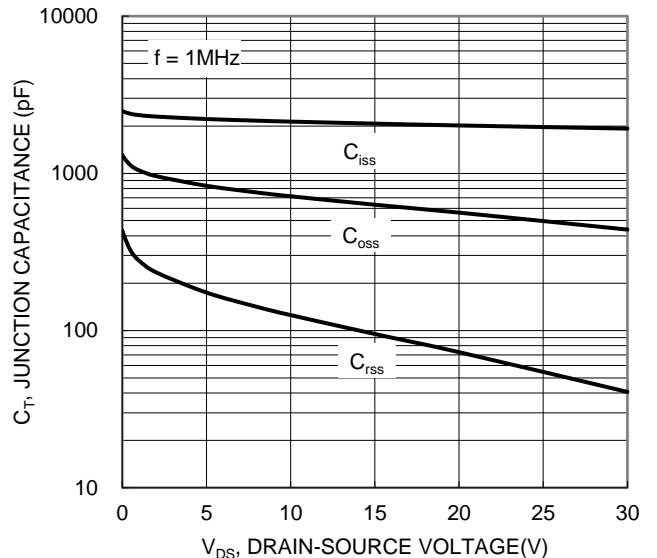


Figure 10. Typical Junction Capacitance

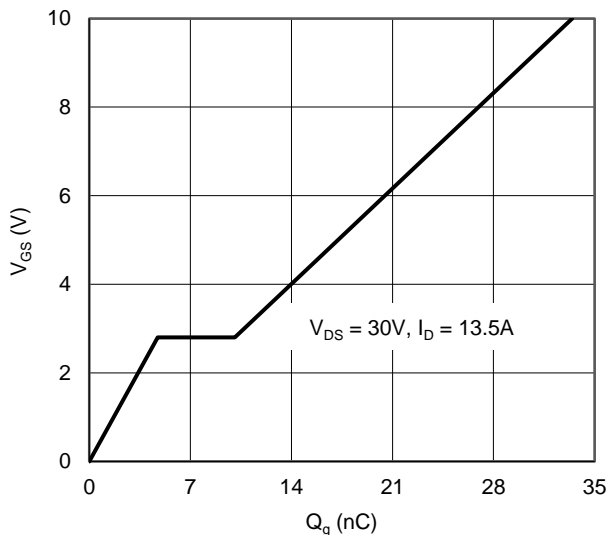


Figure 11. Gate Charge

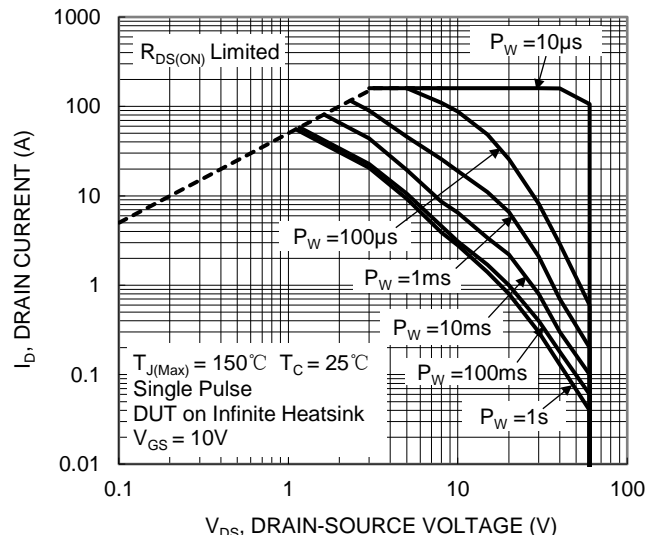


Figure 12. SOA, Safe Operation Area

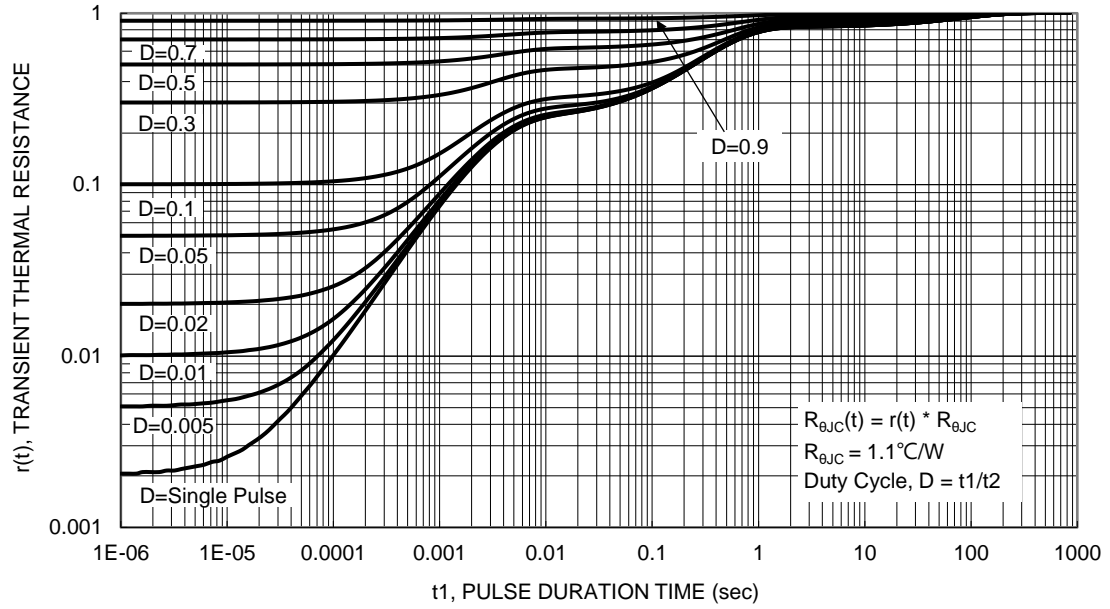


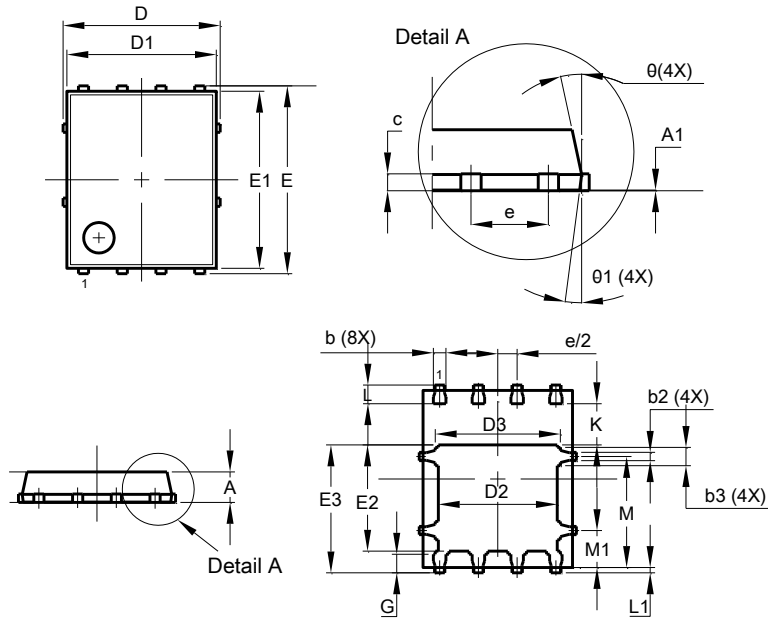
Figure 13. Transient Thermal Resistance

**Package Outline Dimensions**

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

Site 1:

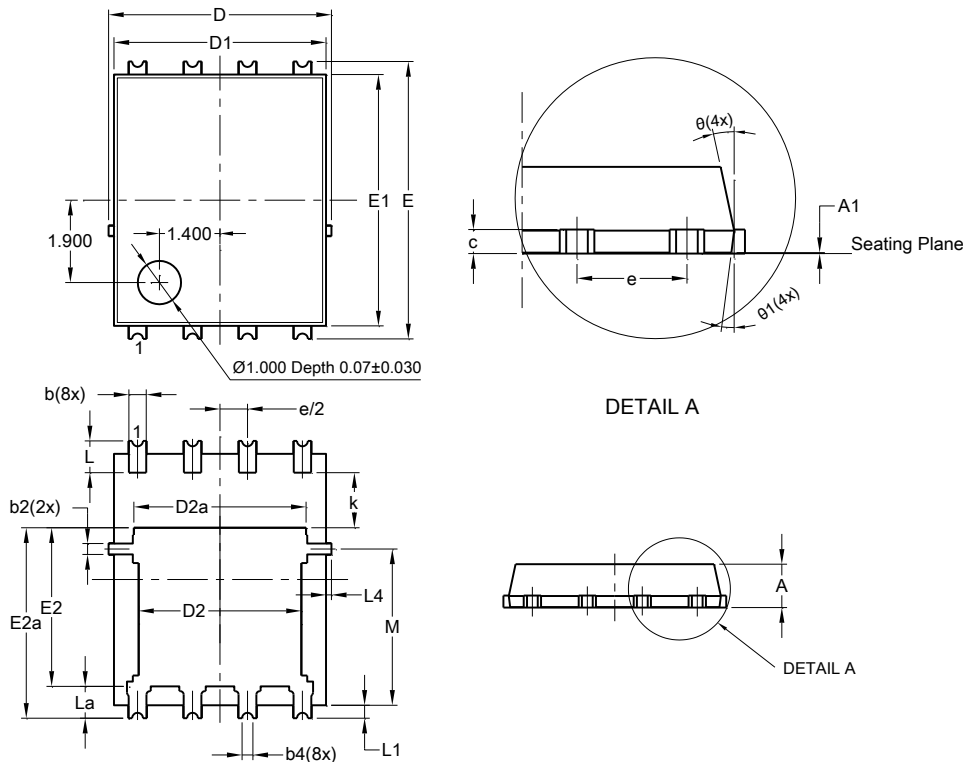
**PowerDI5060-8**



PowerDI5060-8			
Dim	Min	Max	Typ
A	0.90	1.10	1.00
A1	0.00	0.05	-
b	0.33	0.51	0.41
b2	0.200	0.350	0.273
b3	0.40	0.80	0.60
c	0.230	0.330	0.277
D	5.15 BSC		
D1	4.70	5.10	4.90
D2	3.70	4.10	3.90
D3	3.90	4.30	4.10
E	6.15 BSC		
E1	5.60	6.00	5.80
E2	3.28	3.68	3.48
E3	3.99	4.39	4.19
e	1.27 BSC		
G	0.51	0.71	0.61
K	0.51	-	-
L	0.51	0.71	0.61
L1	0.100	0.200	0.175
M	3.235	4.035	3.635
M1	1.00	1.40	1.21
theta	10°	12°	11°
theta1	6°	8°	7°
<b>All Dimensions in mm</b>			

Site 2:

**PowerDI5060-8/SWP (Type UX)**



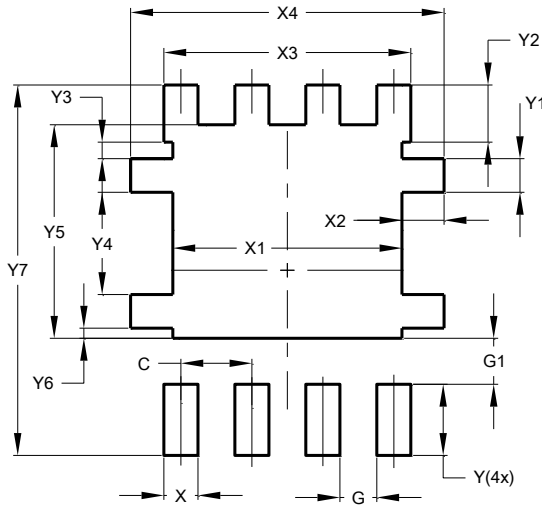
PowerDI5060-8/SWP (Type UX)			
Dim	Min	Max	Typ
A	0.90	1.10	1.00
A1	0	0.05	--
b	0.30	0.50	0.41
b2	0.20	0.35	0.25
b4	0.25REF		
c	0.230	0.330	0.277
D	5.15 BSC		
D1	4.70	5.10	4.90
D2	3.56	3.96	3.76
D2a	3.78	4.18	3.98
E	6.40 BSC		
E1	5.60	6.00	5.80
E2	3.46	3.86	3.66
E2a	4.195	4.595	4.395
e	1.27BSC		
k	1.05	--	--
L	0.635	0.835	0.735
La	0.635	0.835	0.735
L1	0.200	0.400	0.300
L1a	0.050REF		
L4	0.025	0.225	0.125
M	3.205	4.005	3.605
theta	10°	12°	11°
theta1	6°	8°	7°
<b>All Dimensions in mm</b>			

**Suggested Pad Layout**

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

Site 1:

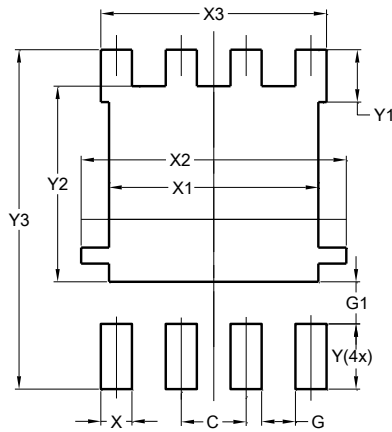
**PowerDI5060-8**



Dimensions	Value (in mm)
C	1.270
G	0.660
G1	0.820
X	0.610
X1	4.100
X2	0.755
X3	4.420
X4	5.610
Y	1.270
Y1	0.600
Y2	1.020
Y3	0.295
Y4	1.825
Y5	3.810
Y6	0.180
Y7	6.610

Site 2:

**PowerDI5060-8/SWP (Type UX)**



Dimensions	Value (in mm)
C	1.270
G	0.660
G1	0.820
X	0.610
X1	4.100
X2	5.190
X3	4.420
Y	1.270
Y1	1.020
Y2	3.810
Y3	6.610

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